

Features

300 Watts peak pulse power ($t_p = 8/20\mu s$)
Unidirectional and unidirectional configurations
Solid-state silicon-avalanche technology
Low clamping voltage
Low leakage current
IEC 61000-4 $\pm 20kV_{contact}$ $\pm 20kV_{air}$
IEC 61000-4-4 (EFT) 40A (5/50ns)
IEC 61000-4-5 (Lightning) 10A (8/20 μs)

Mechanical Data

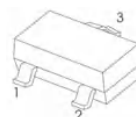
SOT-23 package
Molding compound flammability rating: UL 94V-0
Packaging: Tape and Reel
RoHS/WEEE Compliant

Applications

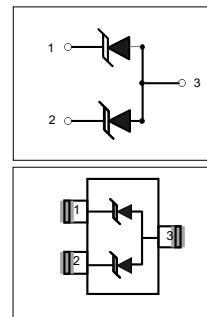
Dataline
Automatic Teller Machines
Net works
Power line

EL15

SOT-23



1.BASE
2.EMITTER
3.COLLECTOR



Schematic & PIN Configuration

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	300	Watts
Peak Pulse Current ($t_p = 8/20\mu s$) (note1)	I_{PP}	10	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	20 20	kV
Lead Soldering Temperature	T_L	260(10seconds)	$^{\circ}C$
Junction Temperature	T_J	-55 to + 125	$^{\circ}C$
Storage Temperature	T_{stg}	-55 to + 125	$^{\circ}C$

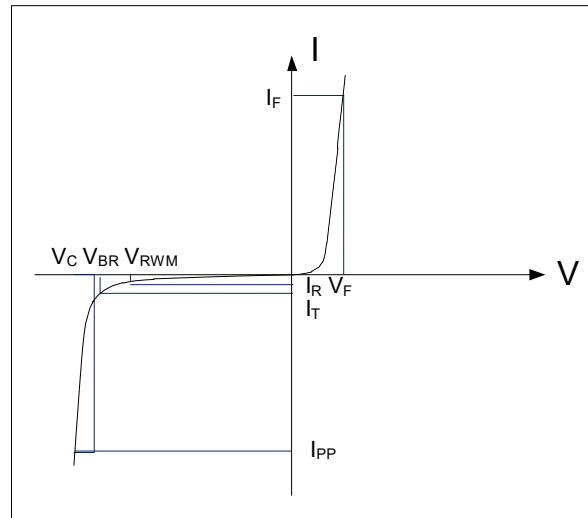
Electrical Characteristics (TA=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V_{RWM}				16	V
Reverse Breakdown Voltage	V_{BR}	$I_T=1mA$	14			V
Reverse Leakage Current	I_R	$V_{RWM}=12V, T=25^{\circ}C$			5	μA
Peak Pulse Current	I_{PP}	$t_p=8/20\mu s$			10	A
Clamping Voltage	V_C	$I_{PP}=10A, t_p=8/20\mu s$			30	V
Junction Capacitance	C_j	$V_R=0V, f=1MHz$ (Pin 1 to Pin 2)		90		pF

Electrical Parameters (TA = 25°C unless otherwise noted)

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current

Note: 8/20 μs pulse waveform.



RATING AND CHARACTERISTIC CURVES

Figure 1: Peak Pulse Power vs. Pulse Time

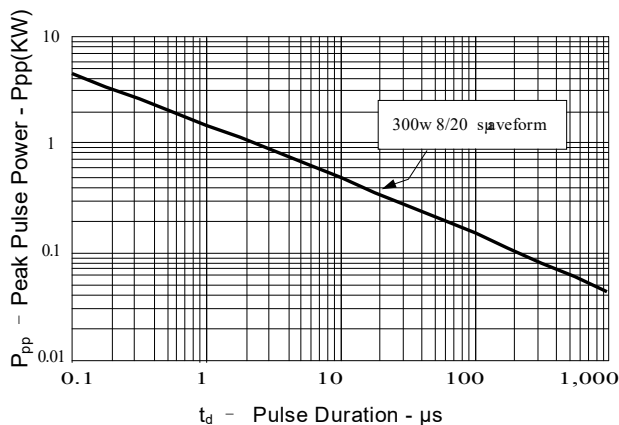


Figure 2: Power Derating Curve

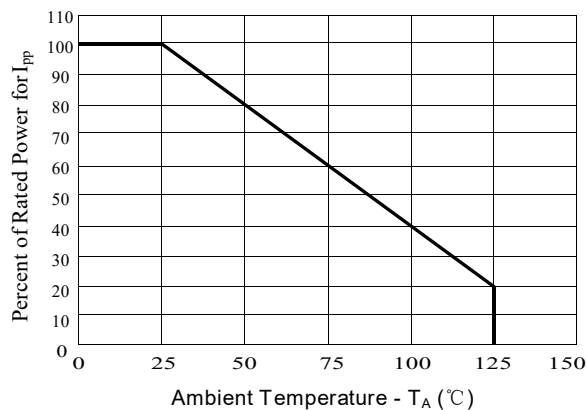


Figure3: Pulse Waveform

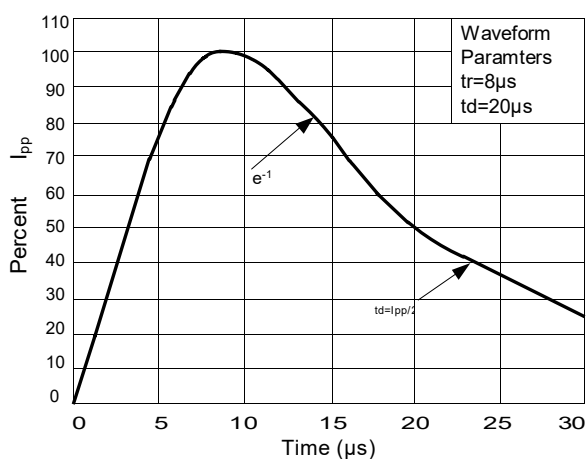
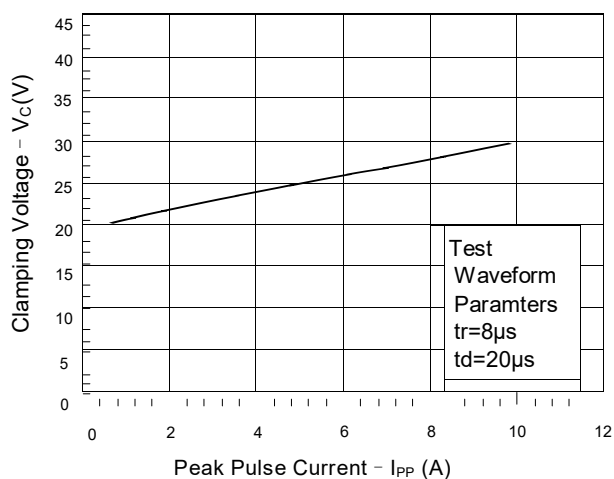
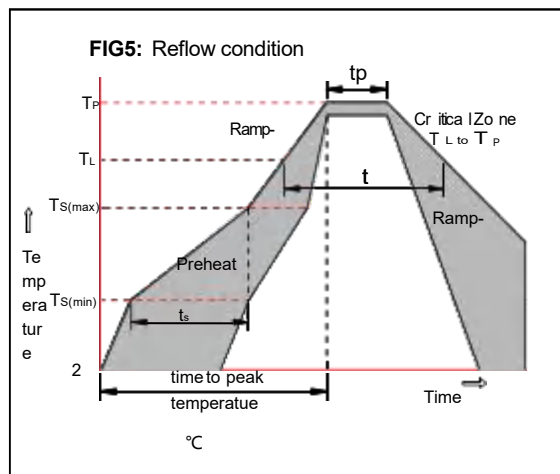


Figure 4: Clamping Voltage vs. Ipp



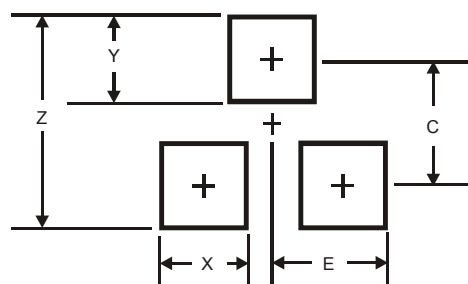
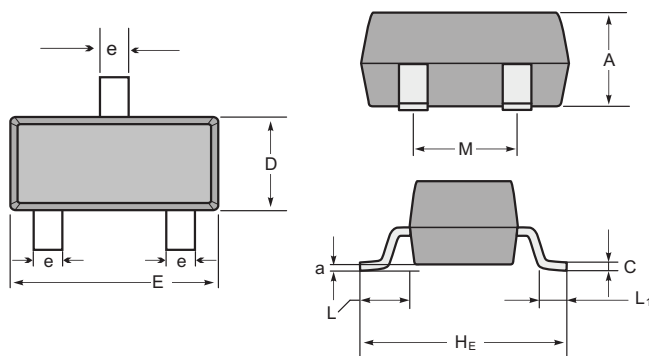
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



Package Dimensions & Suggested Pad Layout

SOT23

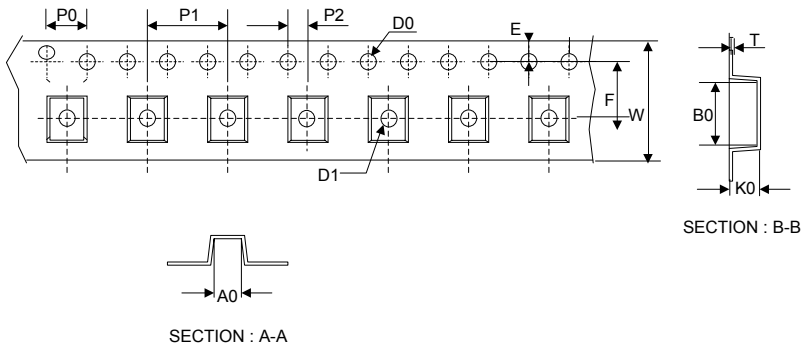
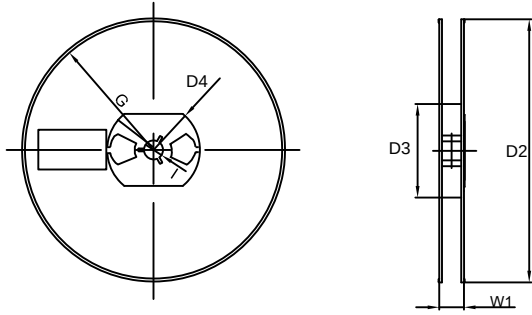


SOT-23 mechanical data

UNIT	A	C	D	E	H _E	e	M	L	L ₁	a
mm	max	1.1	0.15	1.4	3.0	2.6	0.5	1.95	0.55 (ref)	0.36 (ref)
	min	0.9	0.08	1.2	2.8	2.2	0.3	1.7		0.15
mil	max	43	6	55	118	102	20	77	22 (ref)	14 (ref)
	min	35	3	47	110	87	12	67		6

Dimensions	SOT23
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

Tape & reel specification

Tape		Symbol	Dimension (mm)
		P0	4.00±0.10
		P1	4.00±0.10
		P2	2.00±0.10
		D0	1.55±0.10
		D1	1.05±0.10
		E	1.55±0.10
		F	3.60±0.10
		W	8.00±0.10
		A0	3.80±0.20
		B0	3.25±0.20
		K0	1.45±0.10
		T	0.25±0.05
		D2	178.0±3.0
		D3	55Min.
		D4	R24.0±3.0
7" Reel		G	R82.0±3.0
		I	13.0±2.0
		W1	11.0±3.0
		Quantity: 3000PCS	